PRODUCT BRIEF
Intel Thermal Solution HTS1155 LP

Intel® Active Thermal Solution HTS 1155LP Standard Low Profile Intel Boxed Thermal Solution for Thin Mini-ITX

Product Overview

As desktop form factors evolve with an emphasis on thinness (like All-in-Ones and SFF PCs), cooling solutions needed to evolve to support local integration. The Thin Mini-ITX platform is designed for such applications, and Intel's HTS1155LP is a core building block that delivers exceptional performance and enables the evolution of the desktop.

Contents of the Retail Packaged Thermal Solution

1. Heat exchanger (with attached 4x PIM screws and 2x chassis screws pre-attached)
2. Backplate with adhesive
3. Blower with 4 pin connector (PWM controlled)
4. Blower to chassis attach screws 2x in clean plastic bag
5. TIM pillow pack (not pre-applied)
6. Instruction manual

System Requirements

1. Must be a <u>THIN</u> Mini-ITX board as the heat sink requires the CPU to be in a specific location
   -<u>Note:</u> NOT compatible with Regular Mini-ITX boards
2. LGA1155 socket based board with the standard desktop 75x75 mm heat sink attach hole pattern
3. Supports LGA1155 socket based CPUs <u>up to 65 W</u>

Select Technical Specifications

Radiator Dimensions	77 x 77 x 26 mm
Heat Sink Weight	264 grams
Blower Dimensions	80 x 80 x 22 mm
Blower Weight	54 grams
Blower Cable Length	20.5 inches or 521 mm
Fan Speed	1180 – 3380 RPM
Thermal Interface Material (TIM)	TC-1996